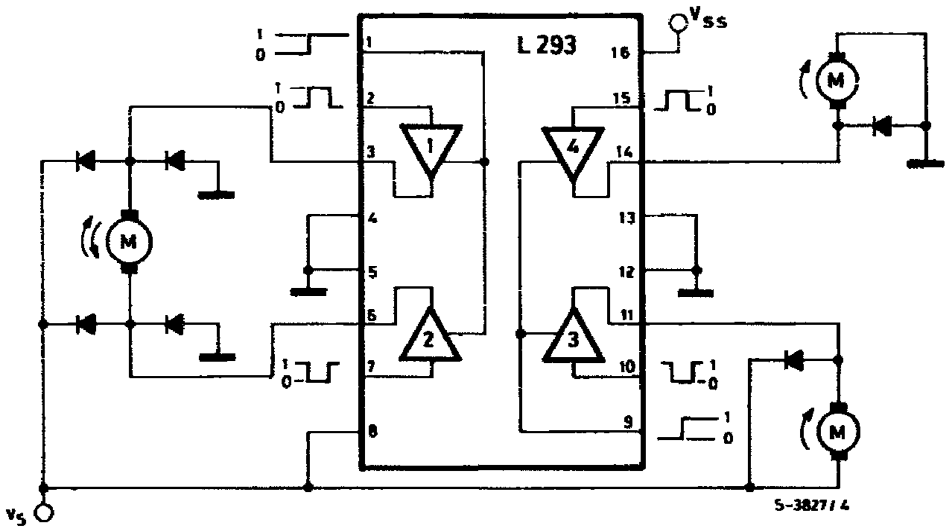
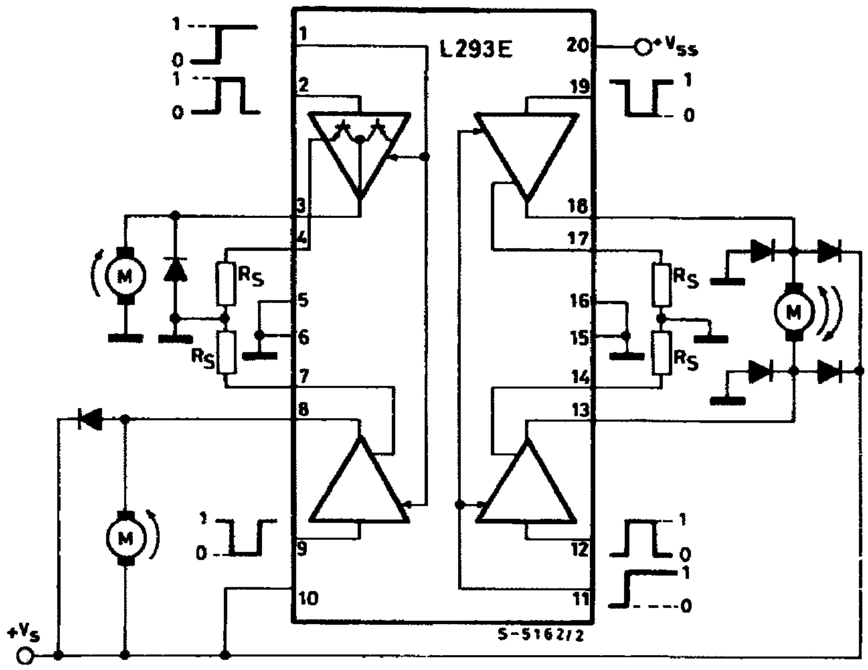
BLOCK DIAGRAMS

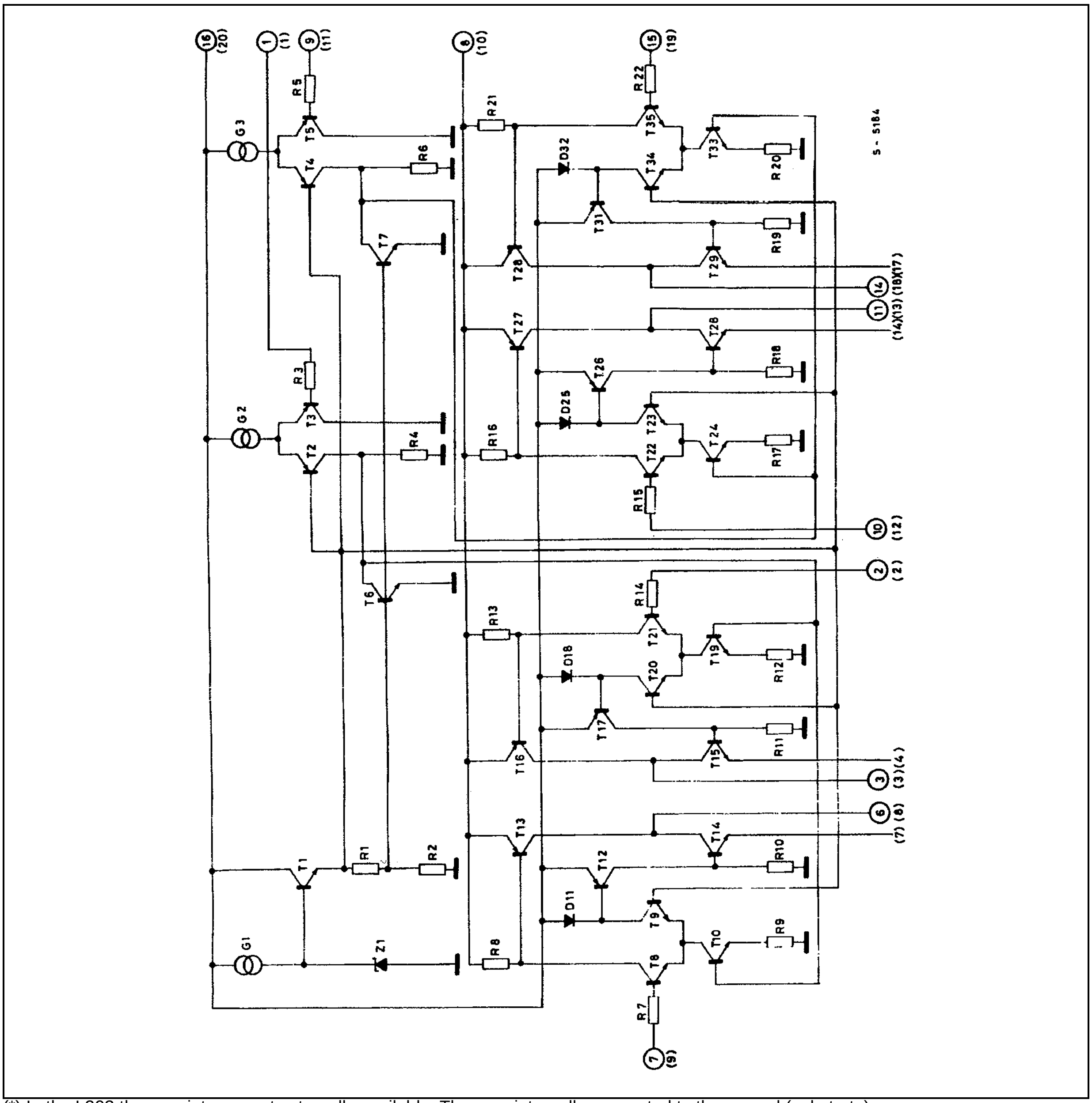
DIP16 - L293B



POWERDIP (16+2+2) - L293E



SCHEMATIC DIAGRAM



(*) In the L293 these points are not externally available. They are internally connected to the ground (substrate).
O Pins of L293 () Pins of L293E.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_S	Supply Voltage	36	V
V_{SS}	Logic Supply Voltage	36	V
V_i	Input Voltage	7	V
V_{inh}	Inhibit Voltage	7	V
I_{out}	Peak Output Current (non repetitive t = 5ms)	2	A
P_{tot}	Total Power Dissipation at $T_{ground-pins}$ = 80°C	5	W
T_{stg}, T_j	Storage and Junction Temperature	–40 to +150	°C

THERMAL DATA

Symbol	Parameter		Value	Unit
$R_{th\ j\text{-}case}$	Thermal Resistance Junction-case	Max.	14	°C/W
$R_{th\ j\text{-}amb}$	Thermal Resistance Junction-ambient	Max.	80	°C/W

ELECTRICAL CHARACTERISTCS

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V_s	Supply Voltage		V_{SS}		36	V
V_{SS}	Logic Supply Voltage		4.5		36	V
I_s	Total Quiescent Supply Current	V_i = L; I_o = 0; V_{inh} = H		2	6	mA
		V_i = h; I_o = 0; V_{inh} = H		16	24	mA
		V_{inh} = L			4	mA
I_{SS}	Total Quiescent Logic Supply Current	V_i = L; I_o = 0; V_{inh} = H		44	60	mA
		V_i = h; I_o = 0; V_{inh} = H		16	22	mA
		V_{inh} = L		16	24	mA
V_{iL}	Input Low Voltage		-0.3		1.5	V
V_{iH}	Input High Voltage	$V_{SS} \leq 7V$	2.3		V_{SS}	V
		$V_{SS} > 7V$	2.3		7	V
I_{iL}	Low Voltage Input Current	V_{il} = 1.5V			-10	µA
I_{iH}	High Voltage Input Current	$2.3V \leq V_{IH} \leq V_{SS} - 0.6V$		30	100	µA
V_{inhL}	Inhibit Low Voltage		-0.3		1.5	V
V_{inhH}	Inhibit High Voltage	$V_{SS} \leq 7V$	2.3		V_{SS}	V
		$V_{SS} > 7V$	2.3		7	V
I_{inhL}	Low Voltage Inhibit Current	V_{inhL} = 1.5V		-30	-100	µA
I_{inhH}	High Voltage Inhibit Current	$2.3V \leq V_{inhH} \leq Vss - 0.6V$			±10	µA
V_{CEsatH}	Source Output Saturation Voltage	I_o = -1A		1.4	1.8	V
V_{CEsatL}	Sink Output Saturation Voltage	I_o = 1A		1.2	1.8	V
V_{SENS}	Sensing Voltage (pins 4, 7, 14, 17) (**)				2	V
t_r	Rise Time	0.1 to 0.9 V_o (*)		250		ns
t_f	Fall Time	0.9 to 0.1 V_o (*)		250		ns
t_{on}	Turn-on Delay	0.5 V_i to 0.5 V_o (*)		750		ns
t_{off}	Turn-off Delay	0.5 V_i to 0.5 V_o (*)		200		ns

* See figure 1
** Referred to L293E

TRUTH TABLE

V_i (each channel)	V_o	V_{inh} (**)
H	H	H
L	L	H
H	X (*)	L
L	X (*)	L

(*) High output impedance
(**) Relative to the considerate channel

Figure 1. Switching Timers

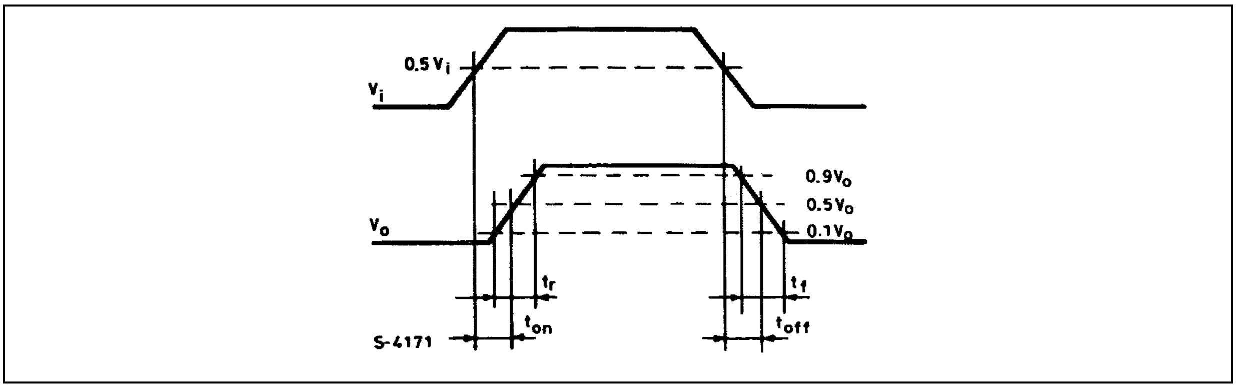


Figure 2. Saturation voltage versus Output Current

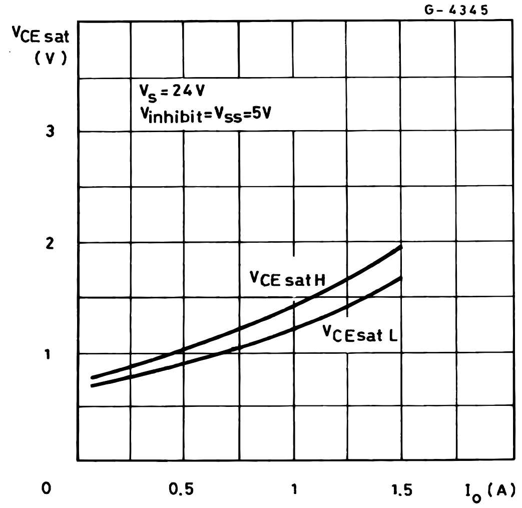


Figure 4. Sink Saturation Voltage versus Ambient Temperature

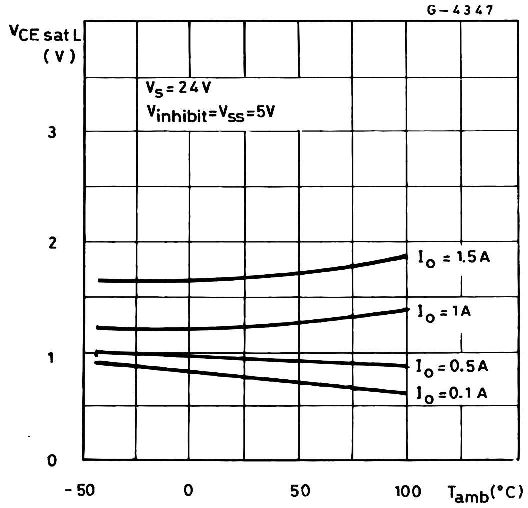


Figure 3. Source Saturation Voltage versus Ambient Temperature

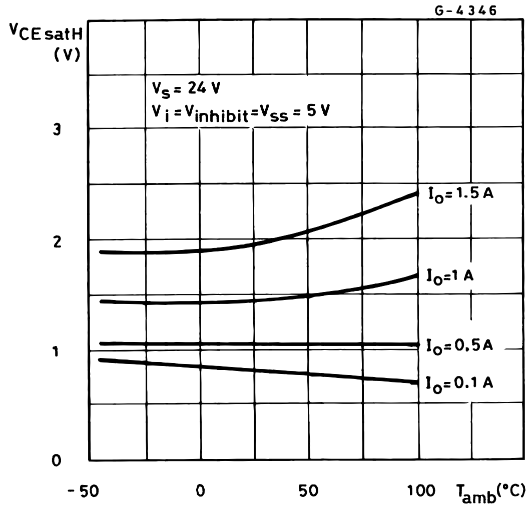


Figure 5. Quiescent Logic Supply Current versus Logic Supply Voltage

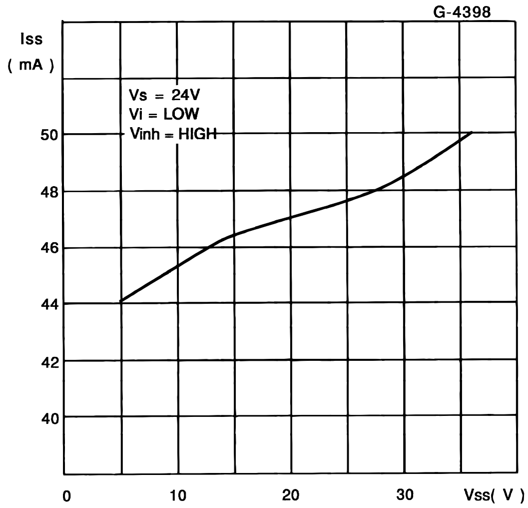


Figure 6. Output Voltage versus Input Voltage

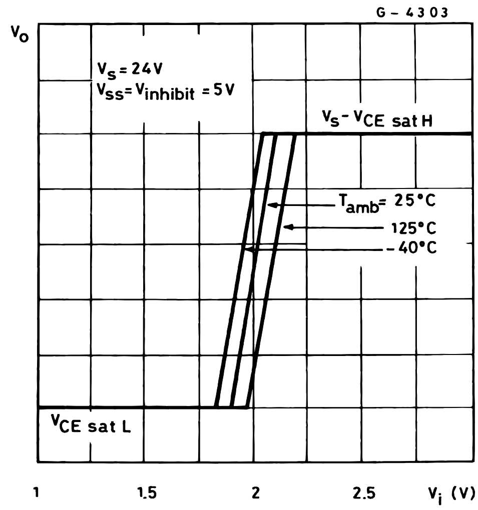
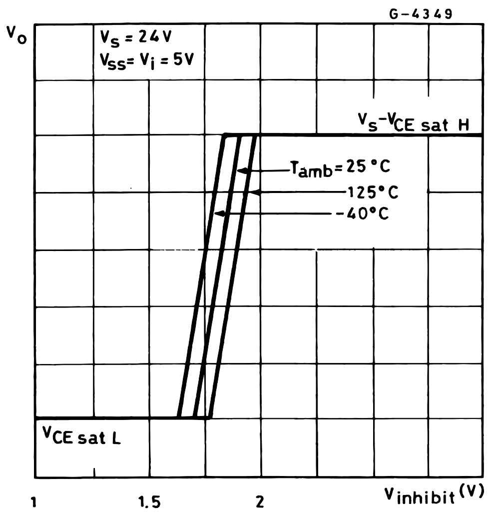
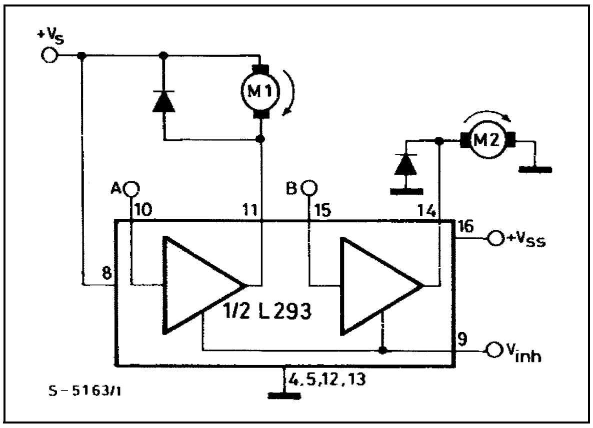


Figure 7. Output Voltage versus Inhibit Voltage



APPLICATION INFORMATION

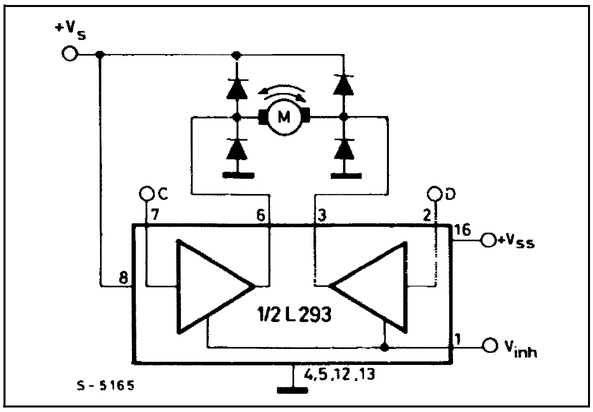
Figure 8. DC Motor Controls (with connection to ground and to the supply voltage)



V_{inh}	A	M1	B	M2
H	H	Fast Motor Stop	H	Run
H	L	Run	L	Fast Motor Stop
L	X	Free Running	X	Free Running
		Motor Stop		Motor Stop

L = Low H = High X = Don't Care

Figure 9. Bidirectional DC Motor Control



Inputs	Function	
V_{inh} = H	C = H ; D = L	Turn Right
	C = L ; D = H	Turn Left
	C = D	Fast Motor Stop
V_{inh} = L	C = X ; D = X	Free Running Motor Stop

L = Low H = High X = Don't Care

Figure 10. Bipolar Stepping Motor Control

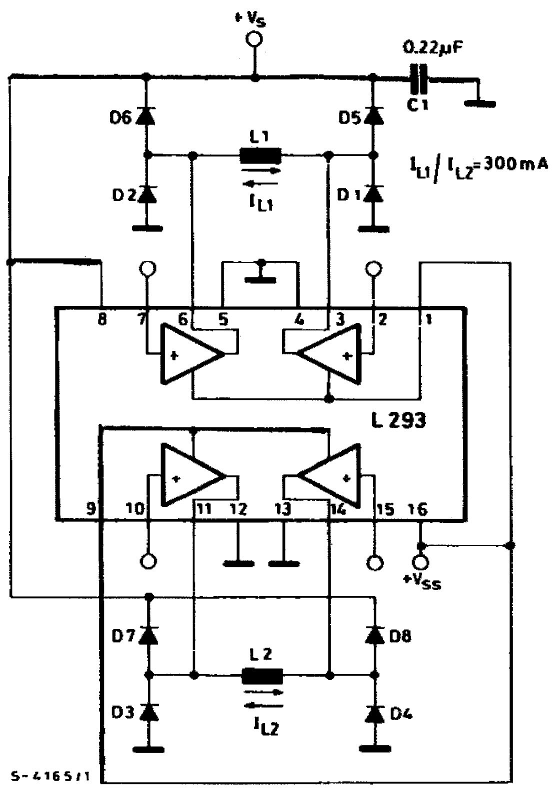
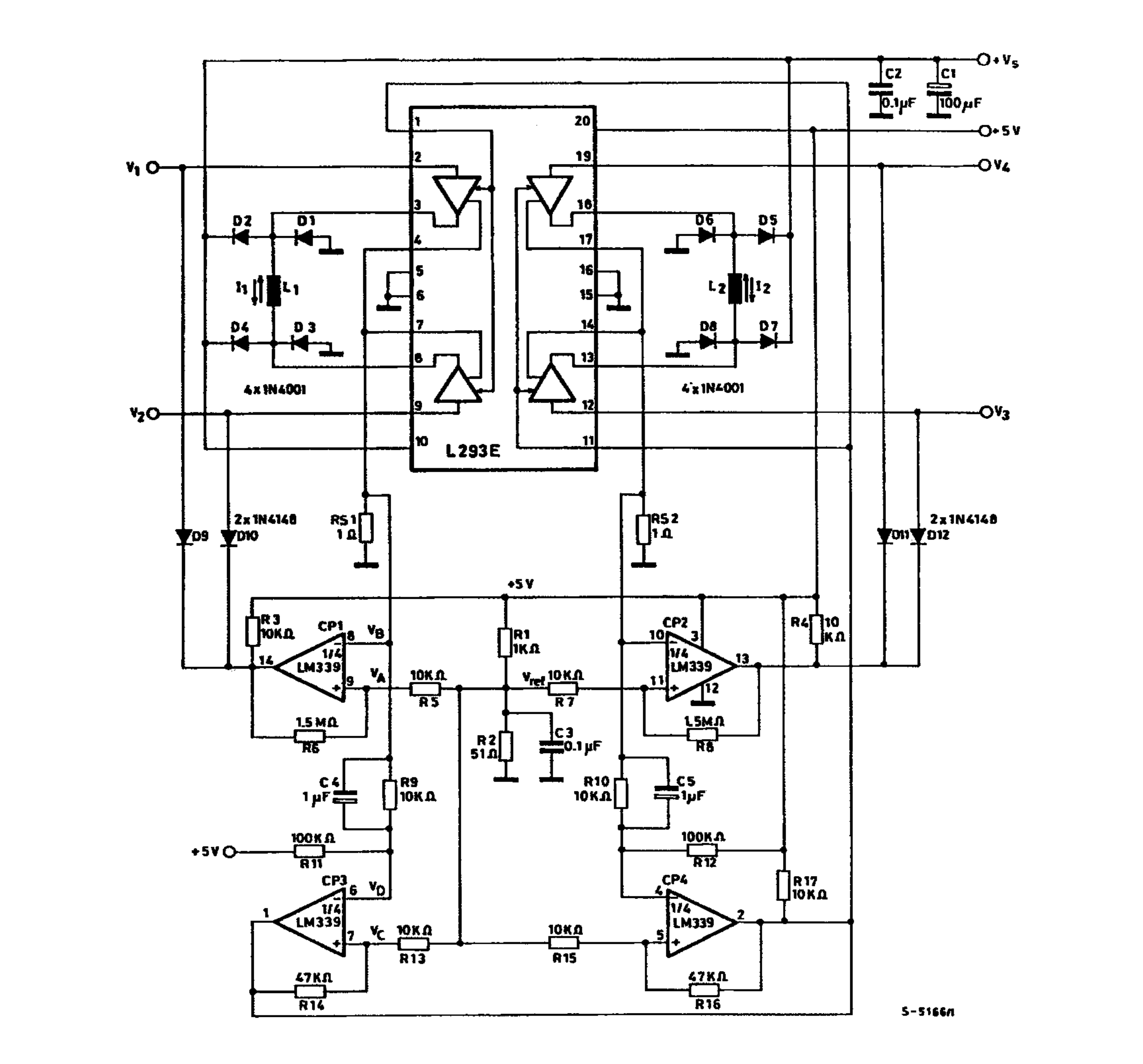


Figure 11. Stepping Motor Driver with Phase Current Control and Short Circuit Protection



MOUNTING INSTRUCTIONS

The $R_{th\ j\text{-}amb}$ of the L293B and the L293E can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board as shown in figure 12 or to an external heatsink (figure 13).

During soldering the pins temperature must not exceed 260°C and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 12. Example of P.C. Board Copper Area which is Used as Heatsink

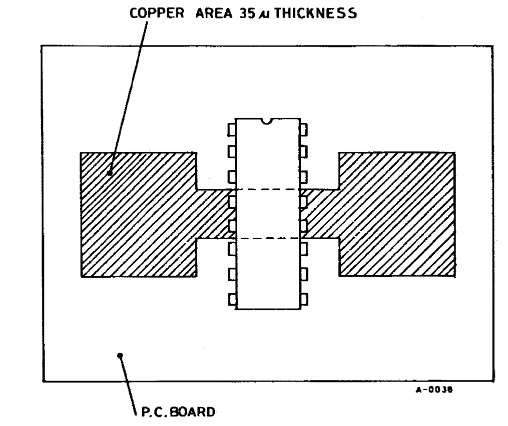
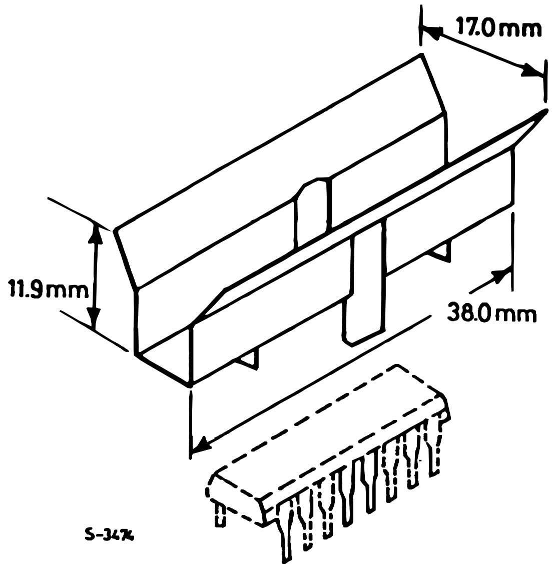
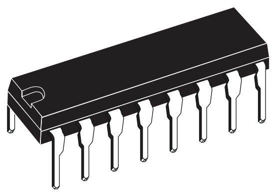


Figure 13. External Heatsink Mounting Example (R_{th} = 30°C/W)

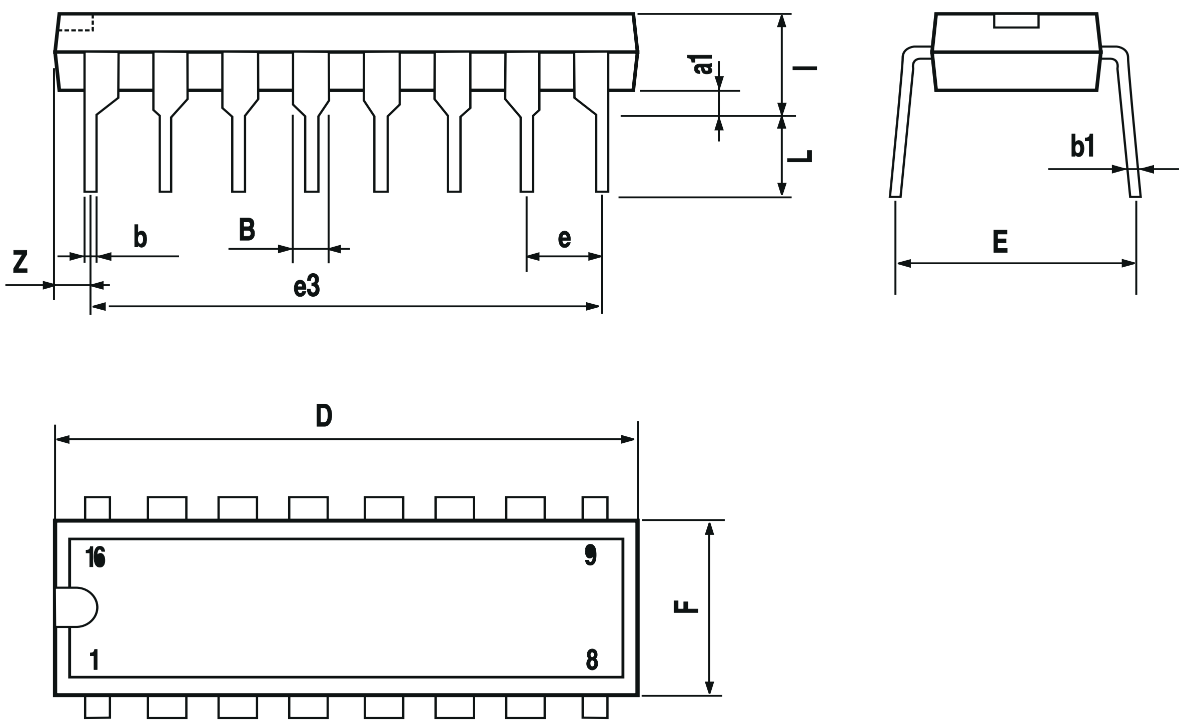


DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050

OUTLINE AND MECHANICAL DATA

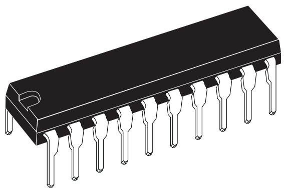


DIP16



DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.85		1.40	0.033		0.055
b		0.50			0.020	
b1	0.38		0.50	0.015		0.020
D			24.80			0.976
E		8.80			0.346	
e		2.54			0.100	
e3		22.86			0.900	
F			7.10			0.280
I			5.10			0.201
L		3.30			0.130	
Z			1.27			0.050

OUTLINE AND MECHANICAL DATA



Powerdip 20